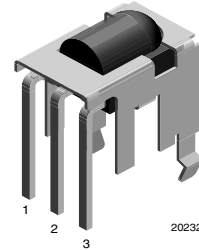


IR Receiver Modules for Remote Control Systems

Description

The TSOP392..CZ1 - series are miniaturized receivers for infrared remote control systems. PIN diode and preamplifier are assembled on lead frame, the epoxy package is designed as IR filter.

The demodulated output signal can directly be decoded by a microprocessor. TSOP392..CZ1 is the standard IR remote control receiver series, supporting all major transmission codes.



Features

- Photo detector and preamplifier in one package
- Build in filter for carrier frequency of IR signal
- Shielding against electrical field disturbance
- TTL and CMOS compatibility
- Output active low
- Low power consumption
- Supply voltage range: 2.7 V to 5.5 V
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



Special Features

- Improved immunity against ambient light
- Suitable burst length ≥ 10 cycles/burst

Mechanical Data

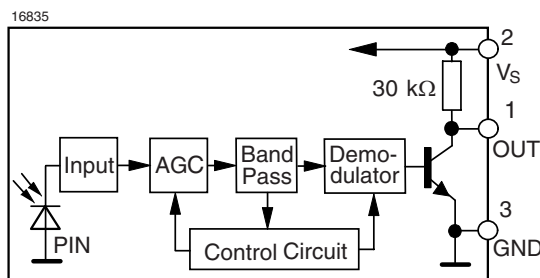
Pinning:

1 = OUT, 2 = V_S , 3 = GND

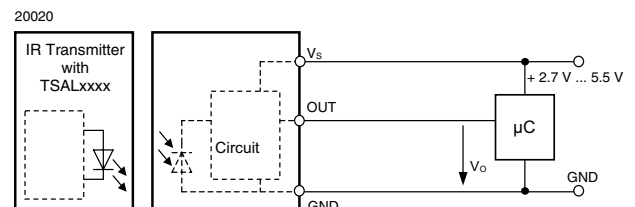
Parts Table

Part	Carrier Frequency
TSOP39230CZ1	30 kHz
TSOP39233CZ1	33 kHz
TSOP39236CZ1	36 kHz
TSOP39237CZ1	36.7 kHz
TSOP39238CZ1	38 kHz
TSOP39240CZ1	40 kHz
TSOP39256CZ1	56 kHz

Block Diagram



Application Circuit



No external components are required

Absolute Maximum Ratings

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Supply Voltage	(Pin 2)	V_S	- 0.3 to + 6.0	V
Supply Current	(Pin 2)	I_S	3	mA
Output Voltage	(Pin 1)	V_O	- 0.3 to ($V_S + 0.3$)	V
Output Current	(Pin 1)	I_O	10	mA
Junction Temperature		T_j	100	$^{\circ}\text{C}$
Storage Temperature Range		T_{stg}	- 25 to + 85	$^{\circ}\text{C}$
Operating Temperature Range		T_{amb}	- 25 to + 85	$^{\circ}\text{C}$
Power Consumption	($T_{amb} \leq 85\text{ }^{\circ}\text{C}$)	P_{tot}	30	mW
Soldering Temperature	$t \leq 10\text{ s}$, 1 mm from case	T_{sd}	260	$^{\circ}\text{C}$

Electrical and Optical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Supply Current (Pin 2)	$E_v = 0$, $V_S = 3.3\text{ V}$	I_{SD}	1.0	1.3	1.6	mA
	$E_v = 40\text{ klx}$, sunlight	I_{SH}		1.4		mA
Supply Voltage		V_S	2.7		5.5	V
Transmission Distance	$E_v = 0$, test signal see fig. 1, IR diode TSAL6200, $I_F = 400\text{ mA}$	d		30		m
Output Voltage Low (Pin 1)	$I_{OSL} = 0.5\text{ mA}$, $E_e = 0.7\text{ mW/m}^2$, test signal see fig. 1	V_{OSL}			250	mV
Minimum Irradiance (30 - 40 kHz)	$V_S = 3\text{ V}$ Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ min}$		0.4	0.6	mW/m^2
Minimum Irradiance (56 kHz)	$V_S = 3\text{ V}$ Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ min}$		0.5	0.7	mW/m^2
Minimum Irradiance (30 - 40 kHz)	$V_S = 5\text{ V}$ Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ min}$		0.55	0.7	mW/m^2
Minimum Irradiance (56 kHz)	$V_S = 5\text{ V}$ Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ min}$		0.65	0.8	mW/m^2
Maximum Irradiance	$t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$, test signal see fig. 1	$E_{e\ max}$	30			W/m^2
Directivity	Angle of half transmission distance	$\phi_{1/2}$		± 45		deg

Typical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

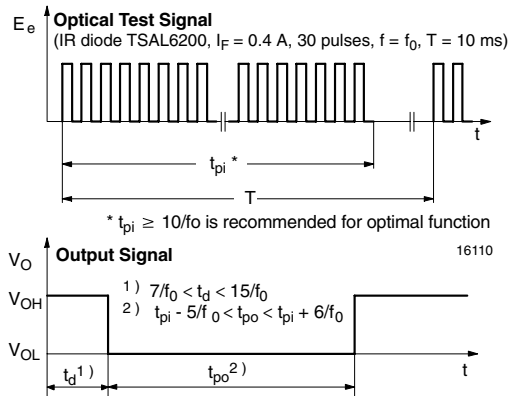


Figure 1. Output Function

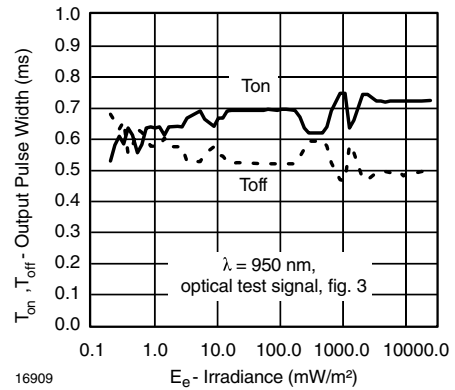


Figure 4. Output Pulse Diagram

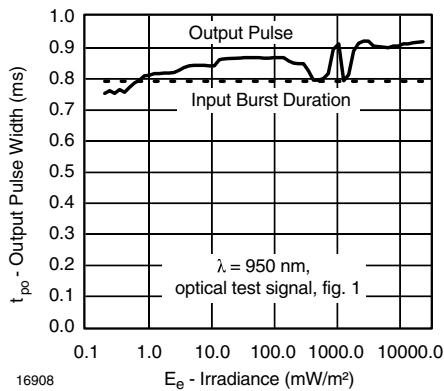


Figure 2. Pulse Length and Sensitivity in Dark Ambient

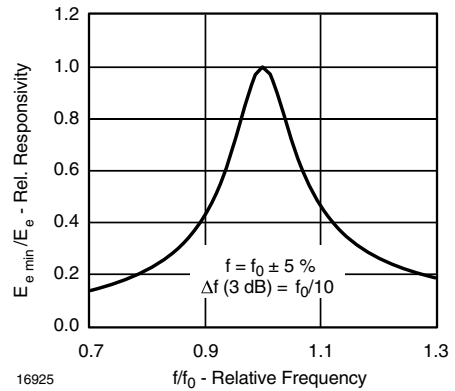


Figure 5. Frequency Dependence of Responsivity

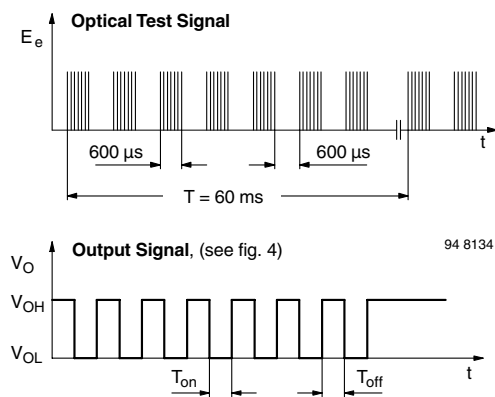


Figure 3. Output Function

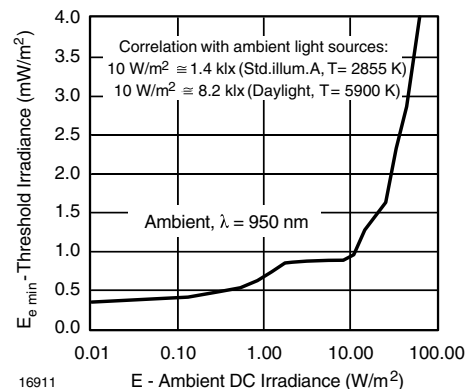


Figure 6. Sensitivity in Bright Ambient

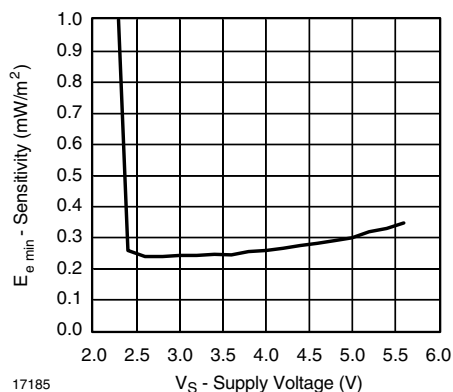


Figure 7. Sensitivity vs. Supply Voltage Disturbances

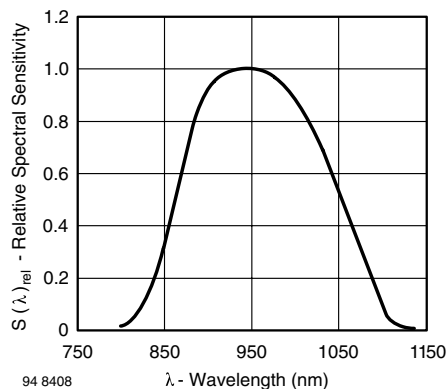


Figure 10. Relative Spectral Sensitivity vs. Wavelength

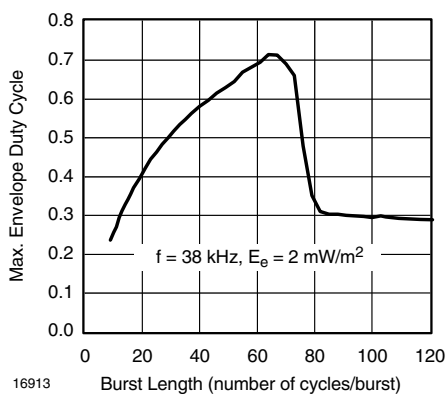


Figure 8. Max. Envelope Duty Cycle vs. Burstlength

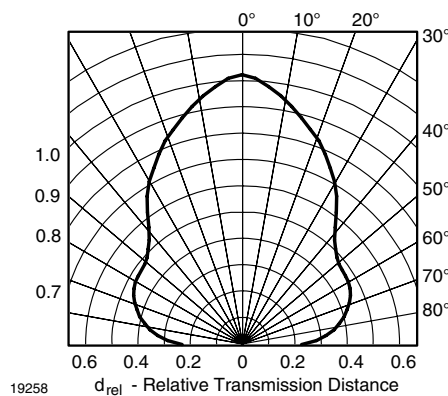


Figure 11. Horizontal Directivity ϕ_x

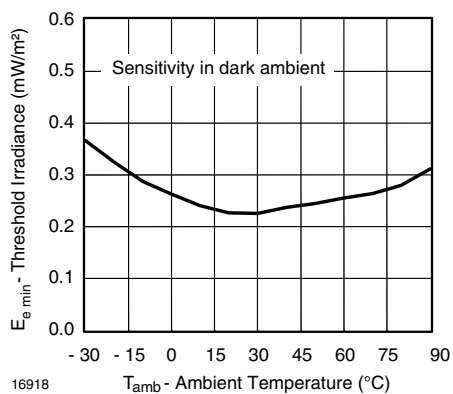


Figure 9. Sensitivity vs. Ambient Temperature

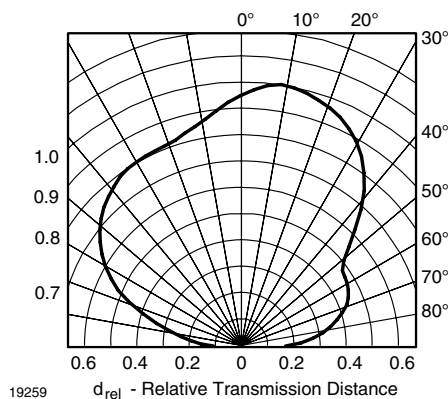


Figure 12. Vertical Directivity ϕ_y

Suitable Data Format

The circuit of the TSOP392..CZ1 is designed in that way that unexpected output pulses due to noise or disturbance signals are avoided. A bandpass filter, an integrator stage and an automatic gain control are used to suppress such disturbances.

The distinguishing mark between data signal and disturbance signal are carrier frequency, burst length and duty cycle.

The data signal should fulfill the following conditions:

- Carrier frequency should be close to center frequency of the bandpass (e. g. 38 kHz).
- Burst length should be 10 cycles/burst or longer.
- After each burst which is between 10 cycles and 70 cycles a gap time of at least 14 cycles is necessary.
- For each burst which is longer than 1.8 ms a corresponding gap time is necessary at some point in the data stream. This gap time should be at least 4 times longer than the burst.
- Up to 800 short bursts per second can be received continuously.

Some examples for suitable data format are: NEC Code (repetitive pulse), NEC Code (repetitive data), Toshiba Micom Format, Sharp Code, RC5 Code, RC6 Code, R-2000 Code, Sony Code.

When a disturbance signal is applied to the TSOP392..CZ1 it can still receive the data signal. However the sensitivity is reduced to such a level that no unexpected pulses will occur.

Some examples for such disturbance signals which are suppressed by the TSOP392..CZ1 are:

- DC light (e.g. from tungsten bulb or sunlight)
- Continuous signal at 38 kHz or at any other frequency
- Signals from fluorescent lamps with electronic ballast with high or low modulation (see Figure 13 or Figure 14).

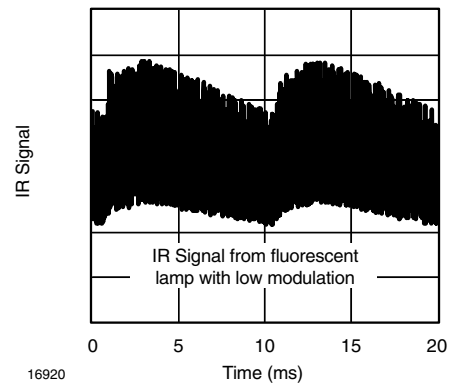


Figure 13. IR Signal from Fluorescent Lamp with low Modulation

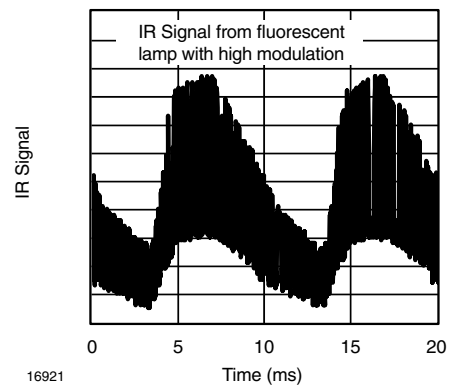


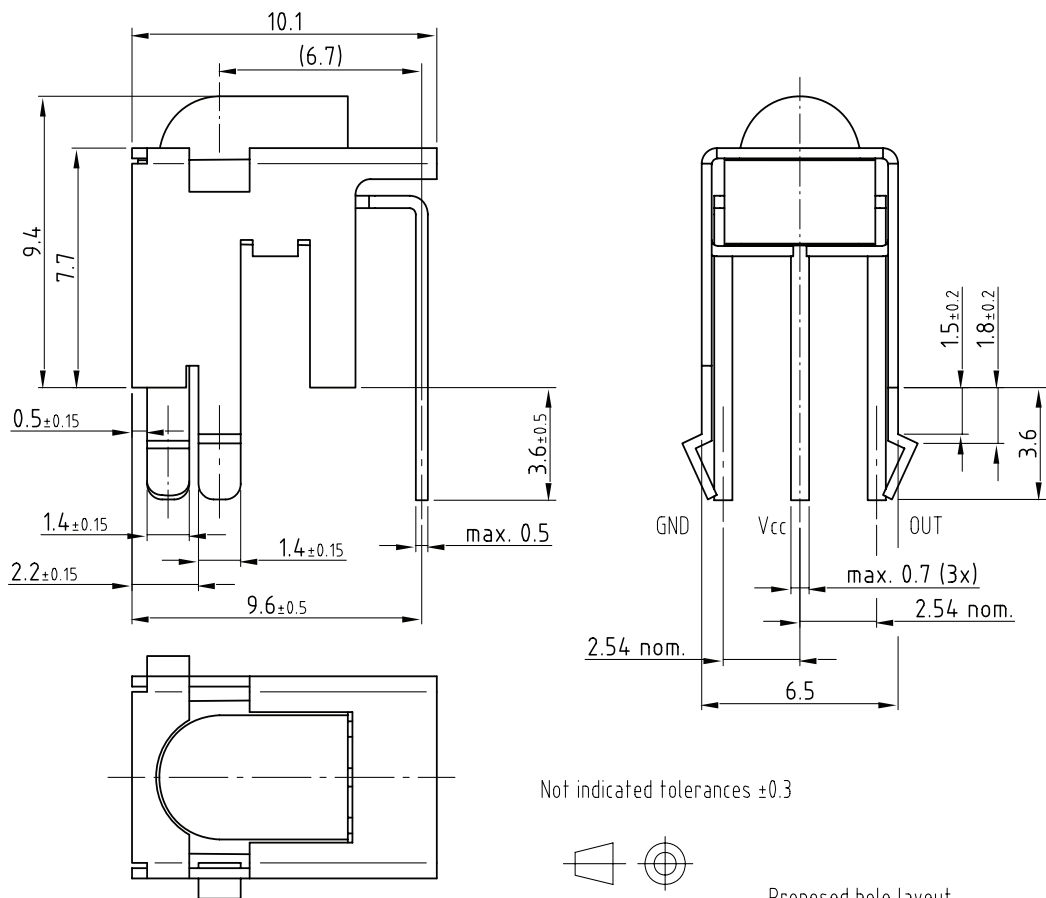
Figure 14. IR Signal from Fluorescent Lamp with high Modulation

TSOP392..CZ1

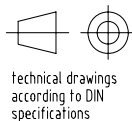
Vishay Semiconductors



Package Dimensions

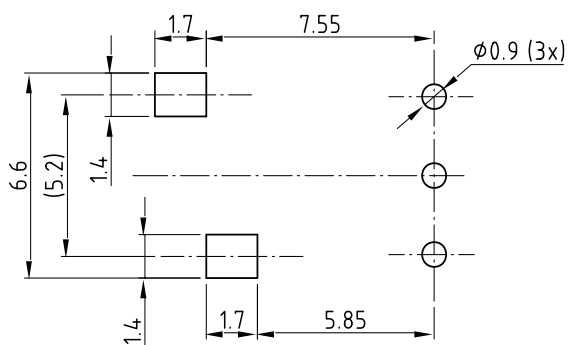


Not indicated tolerances ±0.3



technical drawings according to DIN specifications

Proposed hole layout from component side (for reference only)



Drawing refers to following types:
Drawing no.: 6.550-5288.01-4
Issue: 1; 13.09.06

TSOP92.. CZ.
TSOP592.. CZ.

20231



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

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